

ABSTRACT

A composition for protective film formation capable of forming a protective film excellent in attachability by a tape mounter or the like, with good visibility at a laser-printed portion and heat dissipation properties, allowing a protective film-equipped chip having high reliability to be manufactured, and a sheet for protective film formation and a protective film-equipped chip are provided. The composition for protective film formation contains a polymer component (A), a curable component (B), and a heat conductive filler (C) having an average particle size of 2.0 to 10.0 μm . The content of components that are liquid at 25°C contained in the composition for protective film formation is 20 to 70 parts by mass relative to 100 parts by mass of the total of the (A) component and the (B) component. The content of the (C) component is 40 to 65 volume% relative to the total amount of the composition for protective film formation.